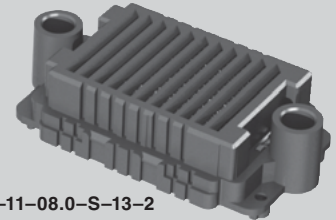


HDAM-11-12.0-S-13-2



HDAF-11-08.0-S-13-2

(2,00 mm) .0787"

HDAM, HDAF SERIES

# RUGGED ELEVATED HIGH DENSITY ARRAY

HDAM Mates with:  
HDAF  
HDAF Mates with:  
HDAM

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HDAM](http://www.samtec.com?HDAM) or [www.samtec.com?HDAF](http://www.samtec.com?HDAF)

**Insulator Material:**  
Black LCP

**Contact Material:**  
Copper Alloy

**Plating:**  
Au or Sn over  
50µ" (1,27 µm) Ni

**Current Rating:**  
3.4 A per pin  
(6 adjacent pins powered)

**Operating Temp Range:**  
-55°C to +125°C

**Contact Resistance:** 19 mΩ

**Working Voltage:** 200 VAC

**Mated Cycles:** 100

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

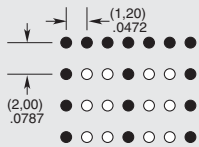
## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

\*2:1 S:G Ratio

## ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
  - Other platings
- Contact Samtec.

**Note:** HD Mezz is a trademark of Molex Incorporated

**Note:** Some lengths, styles and options are non-standard, non-returnable.

HDAM	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and guide pins	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/0.7% Cu Solder Charge	-P = Pick & Place Pad

LEAD STYLE	A
-12.0	(14,41) .567
-17.0	(19,41) .764

• Integrated guide posts

HDAM/HDAF 35 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	9 GHz / 18 Gbps
Differential Pair Signaling	9 GHz / 18 Gbps

\*Data based on simulations using Final Inch® design.  
\*Performance data includes effects of a non-optimized PCB.  
Performance data for other stack heights and complete test data available at [www.samtec.com?HDAM](http://www.samtec.com?HDAM), [www.samtec.com?HDAF](http://www.samtec.com?HDAF) or contact [sig@samtec.com](mailto:sig@samtec.com)

HDAF	NO. OF PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OTHER OPTION
	-11, -15, -23	Specify LEAD STYLE from chart	-S = 30µ" (0,76 µm) Gold on contact area, Matte Tin on tails and weld tabs	-13	-2 = Lead-Free Tin Alloy 95.5% Sn/ 3.8% Ag/ 0.7% Cu Solder Charge	-P = Pick & Place Pad

LEAD STYLE	A
-08.0	(10,51) .414
-18.0	(20,51) .807

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